TOSHIBA PHOTOCOUPLER GaAs IRED & PHOTO-TRIAC

# TLP3041(S),TLP3042(S),TLP3043(S)

OFFICE MACHINE
HOUSEHOLD USE EQUIPMENT
TRIAC DRIVER
SOLID STATE RELAY

The TOSHIBA TLP3041 (S), TLP3042 (S), TLP3043 (S) consist of a zero voltage crossing turn-on photo-triac optically coupled to a gallium arsenide infrared emitting diode in a six lead plastic DIP package.

• Peak Off-State Voltage : 400 V (min)

• Trigger LED Current : 15 mA (max) (TLP3041(S))

10 mA (max) (TLP3042(S))

5 mA (max) (TLP3043(S))

On-State Current : 100 mA (max)
 Isolation Voltage : 5000 Vrms (min)

UL Recognized : UL1577, File No. E67349

• SEMKO Approved : SS EN60065

SS EN60950, File No.9841109

BSI Approved : BS EN60065, File No.8385
 BS EN60950, File No.8386

Option (D4) type

VDE approved: DIN EN60747-5-2

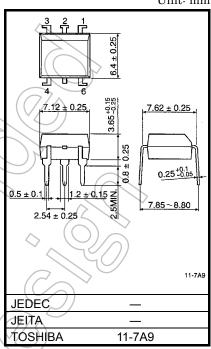
Approved No. 40009302

Maximum operating insulation voltage: 890VPK Highest permissible over voltage: 8000VPK

(Note):When a EN60747-5-2 approved type is needed, please designate the "Option (D4)"

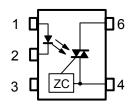
Construction mechanical rating

| \\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\ | 7.62 mm pich   | 10.16 mm pich |  |  |  |
|--|----------------|---------------|--|--|--|
|  | Standard Type  | TLPxxxxF Type |  |  |  |
| Creepage Distance                      | 7.0 mm (Min)   | 8.0 mm (Min)  |  |  |  |
| Clearance                              | ) 7.0 mm (Min) | 8.0 mm (Min)  |  |  |  |
| Insulation Thickness                   | 0.5 mm (Min)   | 0.5 mm (Min)  |  |  |  |
| _                                      |                | · ) )         |  |  |  |



weight: 0.39g (typ.)

## Pin Configuration (top view)



- 1: Anode
- 2: Cathode
- 3: N.C.
- 4:Terminal 1
- 6:Terminal 2

ZC:Zero-cross Circuit



#### Absolute Maximum Ratings (Ta = 25°C)

| CHARACTERISTIC  |   | SYMBOL               | RATING               | UNIT       |         |  |
|---|---|----------------------|----------------------|------------|---------|--|
|   | Forward Current   |                      | I <sub>F</sub>       | 50         | mA      |  |
|   | Forward Current Derating (Ta ≥ 53°C)                        |                      | ΔI <sub>F</sub> / °C | -0.7       | mA / °C |  |
|   | Peak Forward Current (100 µs pulse, 100 pps)                |                      | I <sub>FP</sub>      | 1          | А       |  |
| ΠED   | Power Dissipation   |                      | PD                   | 100        | mW      |  |
|   | Power Dissipation Der (Ta ≥ 25°C)                           | ating                | ΔP <sub>D</sub> / °C | -1.0       | mW / °C |  |
|   | Reverse Voltage   |                      | V <sub>R</sub>       | 5          | V .     | $((// \le)$                            |
|   | Junction Temperature  |                      | Tj                   | 125        | °       |  |
|   | Off-State Output Term                                       | inal Voltage         | $V_{DRM}$            | 400        | V ((    |  |
|   | On-Stage RMS  | Ta = 25°C            | I=                   | 100        | 77      |  |
|   | Current   | Ta = 70°C            | I <sub>T(RMS)</sub>  | 50         | mA      |  |
| œ   | On-State Current Derating (Ta ≥ 25°C)                       |                      | ΔI <sub>T</sub> / °C | -1.1       | mA/°C   | \\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\ |
| DETECTOR  | Peak On-Stage Current (100 µs pulse, 120 pps)               |                      | I <sub>TP</sub>      | 2          |         | \$ C                                   |
| DET   | Peak Nonrepetitive Surge<br>Current (P <sub>W</sub> = 10ms) |                      | I <sub>TSM</sub>     | 1.2        | )<br>A  |  |
|   | Power Dissipation   |                      | PD                   | 300        | mW      |  |
|   | Power Dissipation Derating (Ta ≥ 25°C)                      |                      | ΔP <sub>D</sub> /°C  | -4:0       | mW / °C | 77                                     |
|   | Junction Temperature  |                      | T <sub>j</sub>       | 115        | °C \    | (                                      |
| Storage Temperature Range                               |   | T <sub>stg</sub>     | -55 to 150           | ů          |         |  |
| Operating Temperature Range                             |   |                      | Topr                 | -40 to 100 | ∫ °C    |  |
| Lead Soldering Temperature (10s)                        |   |                      | T <sub>sol</sub>     | 260        | )<br>©  | /                                      |
| Total Package Power Dissipation                         |   |                      | PT                   | 330        | mW      |  |
| Total Package Power Dissipation<br>Derating (Ta ≥ 25°C) |   | ΔP <sub>T</sub> / °C | -4.4                 | mW / °C    |         |  |
|   | tion Voltage<br>1 min., R.H. ≤ 60%)                         | (Note 1)             | BVS                  | 5000       | Vrms    |  |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Device considered a two terminal device: Pins 1, 2 and 3 shorted together and pins 4 and 6 shorted together.

#### **Recommended Operating Conditions**

| CHARACTERISTIC        | SYMBOL           | MIN | TYP. | MAX | UNIT |
|-----------------------|------------------|-----|------|-----|------|
| Supply Voltage        | $V_{AC}$         | _   | _    | 120 | Vac  |
| Forward Current       | l <sub>F</sub> * | 15  | 20   | 25  | mA   |
| Peak On-Stage Current | I <sub>TP</sub>  | _   | _    | 1   | Α    |
| Operating Temperature | T <sub>opr</sub> | -25 |      | 85  | °C   |

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

\*: In the case of TLP3042



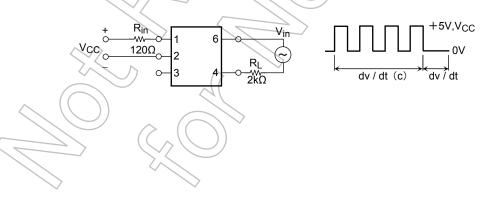
### Individual Electrical Characteristics (Ta = 25°C)

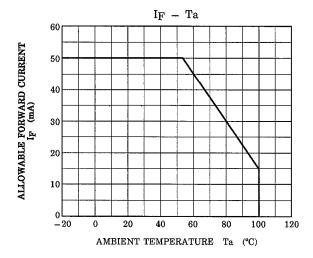
|          | CHARACTERISTIC                                 | SYMBOL           | TEST CONDITION                               | MIN | TYP.  | MAX | UNIT   |
|----------|--|------------------|--|-----|-------|-----|--------|
| LED      | Forward Voltage                                | V <sub>F</sub>   | I <sub>F</sub> = 10mA                        | 1.0 | 1.15  | 1.3 | V      |
|          | Reverse Current                                | I <sub>R</sub>   | V <sub>R</sub> = 5V                          | _   | _     | 10  | μА     |
|          | Capacitance                                    | C <sub>T</sub>   | V = 0, f = 1MHz                              | 7   | 10    | _   | pF     |
| DETECTOR | Peak Off-State Current                         | I <sub>DRM</sub> | V <sub>DRM</sub> = 400V                      |     | 10    | 100 | nA     |
|          | Peak On-Stage Voltage                          | $V_{TM}$         | I <sub>TM</sub> = 100mA                      | (F) | ) 1.7 | 3.0 | V      |
|          | Holding Current                                | lΗ               | (  |     | 0.6   |     | mA     |
|          | Critical Rate of Rise of Off-<br>State Voltage | dv / dt          | V <sub>in</sub> = 120Vrms, Ta = 85°C (Fig.1) | 200 | 500   | l   | V / μs |
|          | Critical Rate of Rise of Commutating Voltage   | dv / dt(c)       | V <sub>in</sub> = 30Vrms, IT = 15mA (Fig.1)  | _   | 0.2   | _   | V / μs |

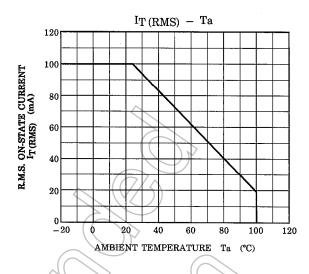
## Coupled Electrical Characteristics (Ta = 25°C)

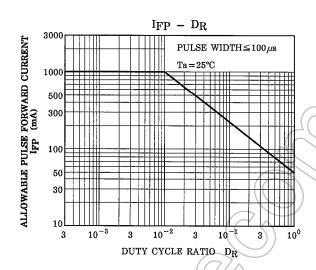
| CHARACTERISTIC             |            | SYMBOL          | TEST CONDITION  | MIN                | TYP.             | MAX | UNIT   |
|----------------------------|------------|-----------------|---|--------------------|------------------|-----|--------|
| Trigger LED Current        | TLP3041(S) | I <sub>FT</sub> |   | 7                  |                  | 15  |        |
|                            | TLP3042(S) |                 | V <sub>T</sub> = 3V   |                    | 5                | 10  | mA     |
|                            | TLP3043(S) | ,               |   |                    | _                | 5   |        |
| Inhibit Voltage            |            | VIH             | I <sub>F</sub> = Rated I <sub>FT</sub>  | \ _                | _                | 40  | V      |
| Leakage in Inhibited State |            | IIH             | I <sub>F</sub> = Rated I <sub>FT</sub><br>V <sub>T</sub> = Rated V <sub>DRM</sub> | _                  | 100              | 300 | μA     |
| Capacitance Input to Outp  | out        | CS              | V <sub>S</sub> = 0, f = 1MHz  | _                  | 0.8              | _   | pF     |
| Isolation Resistance       |            | Rs              | V <sub>S</sub> = 500V (R.H. ≤ 60%)  | 5×10 <sup>10</sup> | 10 <sup>14</sup> | _   | Ω      |
|                            |            | 7               | AC, 1 minute  | 5000               |                  |     | Vrms   |
| Isolation Voltage          |            | BVs             | AC, 1 second (in oil)   | _                  | 10000            |     | VIIIIS |
|                            |            | $\Diamond$      | DC, 1 minute (in oil)   | _                  | 10000            |     | Vdc    |

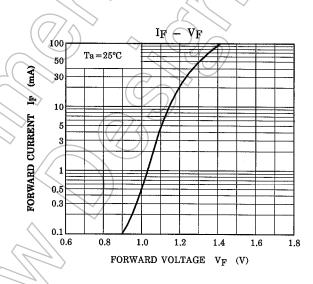
Fig. 1 dv / dt test circuit

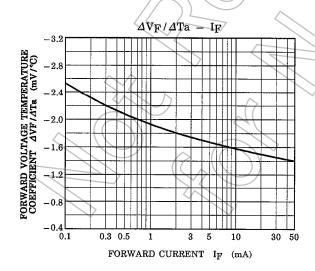


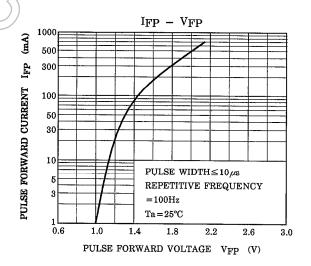


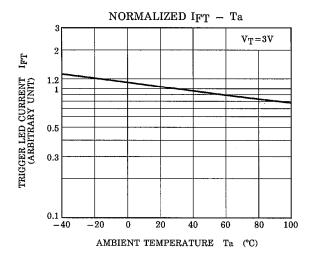


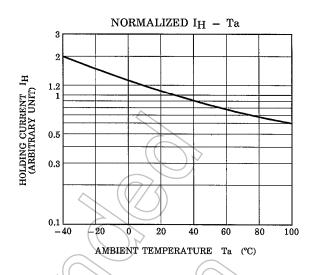


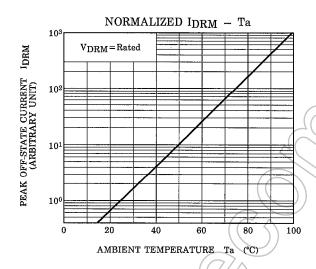


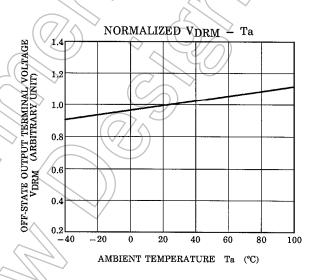


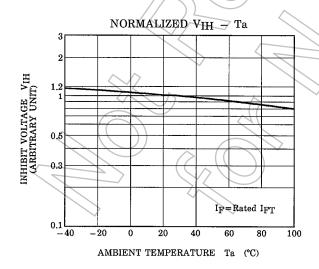


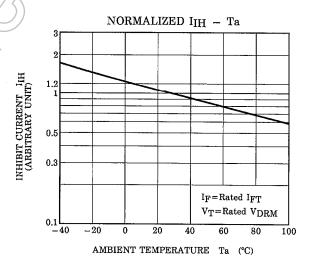














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